

## Full Material Declaration for attached parts list

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## Diotec Semiconductor AG

DUNS number: 330866844

-, Kreuzmattenstr. 4, Heitersheim, 79423, Germany

Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 October 2020 [Approved on 24 January 2022, 09:23 GMT]

## Materials and substances

| Use/Location      | Material Group                                  | % w/w of material in the part | Substances in the material      | CAS Number | % w/w of substance in the material |
|-------------------|-------------------------------------------------|-------------------------------|---------------------------------|------------|------------------------------------|
| Chip (die)        | Other inorganic materials                       | 7.52%                         | Silicon                         | 7440-21-3  | 100%                               |
| Die attach        | Silver plating                                  | 0.55%                         | 1,4-BIS(2,3-EPOXYPROPOXY)BUTANE | 2425-79-8  | 6%                                 |
|                   |                                                 |                               | Epoxy resin 89                  | 26335-32-0 | 12%                                |
|                   |                                                 |                               | Silver                          | 7440-22-4  | 82%                                |
| Encapsulation     | EP (Epoxy resin)                                | 45.83%                        | Carbon black                    | 1333-86-4  | 0.85%                              |
|                   |                                                 |                               | Phenol                          | 108-95-2   | 1.15%                              |
|                   |                                                 |                               | Epoxy resin 89                  | 26335-32-0 | 2%                                 |
|                   |                                                 |                               | Silica                          | 7631-86-9  | 9%                                 |
|                   |                                                 |                               | Quartz sand                     | 60676-86-0 | 87%                                |
| Inner preparation | Copper (e.g. copper amounts in cable harnesses) | 7.42%                         | Copper (metallic)               | 7440-50-8  | 100%                               |
| Leadfinish        | Tin plating                                     | 7.8%                          | Tin                             | 7440-31-5  | 100%                               |
| Leadframe         | Copper (e.g. copper amounts in cable harnesses) | 30.88%                        | Zinc                            | 7440-66-6  | 0.1%                               |
|                   |                                                 |                               | Silver                          | 7440-22-4  | 0.6%                               |
|                   |                                                 |                               | Iron                            | 7439-89-6  | 2.5%                               |
|                   |                                                 |                               | Copper                          | 7440-50-8  | 96.8%                              |

**Attached parts list**

| Part number | Part name              | Part Mass | Part Mass UoM |
|-------------|------------------------|-----------|---------------|
| QFN3x3      | Diode/Transistor Power | 0.1       | g             |

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